

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Silicon TVS Diode

 ESD / transient protection of data and power lines in low voltage applications according to:

IEC61000-4-2 (ESD): ± 25 kV (air) 20 kV (contact)

IEC61000-4-4 (EFT): 50 A / 2.5 kV (5/50 ns)

IEC61000-4-5 (surge): 5.5 A / 80 W (8/20 μs)

• Small form factor (0402 inch): 1.0 x 0.6 x 0.4 mm³

 Bi-directional, symmetrical working voltage up to ± 5.3 V

- Ultralow and symmetric clamping voltage
- ullet Ultralow dynamic resistance 0.4 Ω
- Very fast response time
- Pb-free (RoHS compliant) package

Applications

Recommended to protect audio lines / microphone lines / speaker and headset systems in:

- Mobile phones
- Mobile TV
- Set top boxes
- MP3 players
- Minidisc players
- Portable entertainment electronics



ESD5V3S1B-02LRH



Туре	Package	Configuration	Marking
ESD5V3S1B-02LRH	TSLP-2-17	1 line, bi-directional	E1





Maximum Ratings at $T_A = 25^{\circ}$ C, unless otherwise specified

Parameter	Symbol	Value	Unit
ESD air / contact discharge ¹⁾	V _{ESD}	25 / 20	kV
Peak pulse current $(t_p = 8 / 20 \mu s)^2$	I _{pp}	5.5	А
Peak pulse power ($t_p = 8 / 20 \mu\text{s}^2$)	P_{pk}	80	W
Operating temperature range	T _{op}	-55125	°C
Storage temperature	T _{stg}	-65150	

Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	1
Characteristics	•	•	•		•
Reverse working voltage	V_{RWM}	-5.3	-	5.3	V
Breakdown voltage	$V_{(BR)}$	6	-	-	
$I_{(BR)} = 1 \text{ mA}$					
Reverse current	I _R	-	-	0.1	μΑ
V _R = 3.3 V					
Clamping voltage	V_{CL}				V
$I_{PP} = 1 \text{ A}, t_p = 8/20 \ \mu\text{s}^{2}$		-	8	10	
$I_{PP} = 3.5 \text{ A}, \ t_p = 8/20 \ \mu\text{s}^{2}$		-	10	12	
$I_{PP} = 5.5 \text{ A}, \ t_p = 8/20 \ \mu\text{s}^{2}$		-	11	13	
Diode capacitance	C _T				pF
$V_{R} = 0 \text{ V}, f = 1 \text{ MHz}$		_	17.5	20	
V_{R} = 2.5 V, f = 1 MHz		_	14.5	_	
Dynamic resistance ³⁾ ($t_p = 30 \text{ ns}$)	R _D	-	0.4	-	Ω

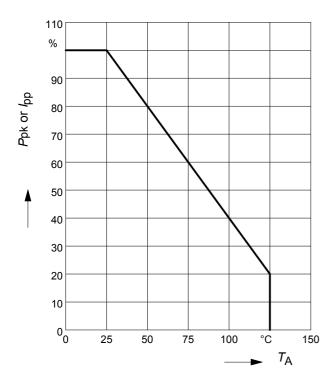
 $^{^{1}}V_{\mbox{ESD}}$ according to IEC61000-4-2

 $^{^2}I_{\mathrm{pp}}$ according to IEC61000-4-5

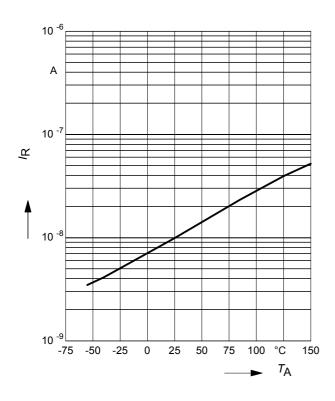
³ according to TLP tests



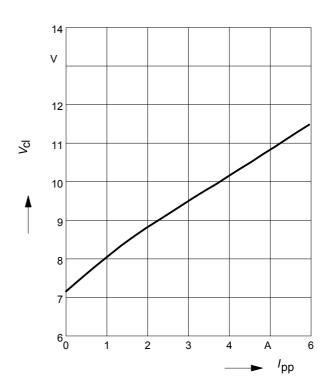
Power derating curve $P_{pk} = f(T_A)$



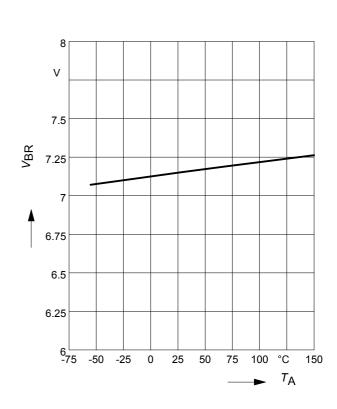
Reverse current $I_R = f(T_A)$ $V_R = 3.3 \text{ V}$



Clamping voltage, $V_{cl} = f(I_{pp})$ $t_p = 8 / 20 \mu s$



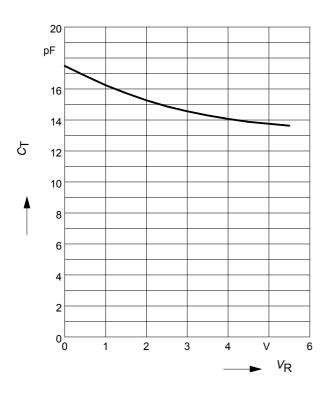
Breakdown voltage $V_{\rm BR}$ = $f(T_{\rm A})$ $I_{\rm R}$ = 1 mA





Diode capacitance $C_T = f(V_R)$

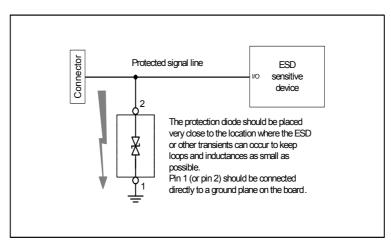
f = 1MHz





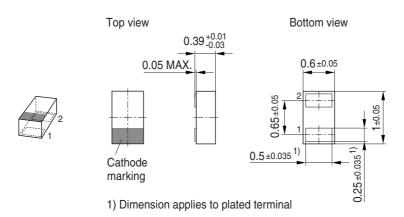
Application example

single channel, bi-directional



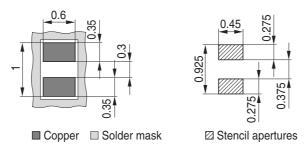


Package Outline

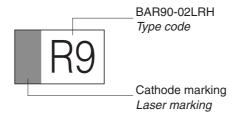


Foot Print

For board assembly information please refer to Infineon website "Packages"

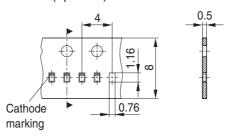


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel Reel ø330 mm = 50.000 Pieces/Reel (optional)



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